

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE2304 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge .This device is suitable for use as a load switch or in PWM applications.

General Features

• $V_{DS} = 30V, I_D = 3.6A$

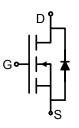
 $R_{DS(ON)}$ < 73m Ω @ V_{GS} =4.5V

 $R_{DS(ON)}$ <46m Ω @ V_{GS} =10V

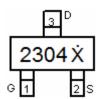
- High power and current handing capability
- Lead free product is acquired
- Surface mount package
- Pb free terminal plating
- RoHS compliant
- Halogen free

Application

- Battery protection
- Load switch
- Power management



Schematic diagram



Marking and pin assignment



SOT-23 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2304 X	NCE2304	SOT-23	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V	
Gate-Source Voltage	V _{GS}	±20	V	
Drain Current-Continuous	I _D	3.6	А	
Drain Current-Pulsed (Note 1)	I _{DM}	15	Α	
Maximum Power Dissipation	P _D	1.7	W	
Operating Junction and Storage Temperature Range	T_{J},T_{STG}	-55 To 150	°C	

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	73.5	°C/W
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Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA



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Parameter	Symbol	Condition	Min	Тур	Max	Unit
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)						•
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	1.05	1.5	2.1	V
Drain-Source On-State Resistance		V _{GS} =4.5V, I _D =3.1A	-	61	73	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =3.6A	-	39	46	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =3.6A	-	11	-	S
Dynamic Characteristics (Note4)			•			•
Input Capacitance	C _{lss}	\/ -45\/\/ -0\/	-	230	-	PF
Output Capacitance	Coss	V_{DS} =15V, V_{GS} =0V, F=1.0MHz	-	40	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.UIVITIZ	-	17	-	PF
Switching Characteristics (Note 4)						•
Turn-on Delay Time	t _{d(on)}		-	10	-	nS
Turn-on Rise Time	t _r	V_{DD} =10V, I_{D} =3.6A	-	50	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =4.5 V , R_{GEN} =6 Ω	-	10	-	nS
Turn-Off Fall Time	t _f		-	20	-	nS
Total Gate Charge	Qg	\/ 45\/ L 0.0A	-	4.0	-	nC
Gate-Source Charge	Q _{gs}	V_{DS} =15V, I_{D} =3.6A,	-	0.75	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	0.65	-	nC
Drain-Source Diode Characteristics			•			•
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =3.6A	-	0.8	1.2	V
Diode Forward Current (Note 2)	Is		-	-	3.6	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

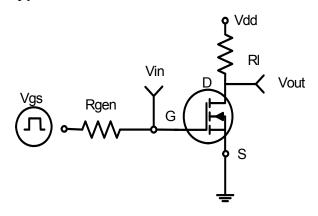
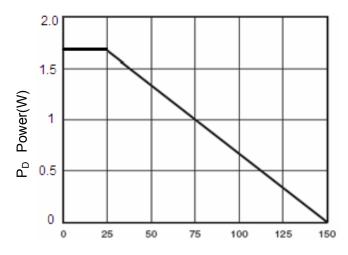


Figure 1:Switching Test Circuit



T_J-Junction Temperature(°C)

Figure 3 Power Dissipation

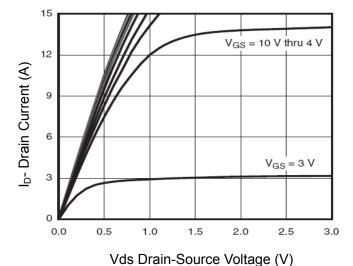


Figure 5 Output Characteristics

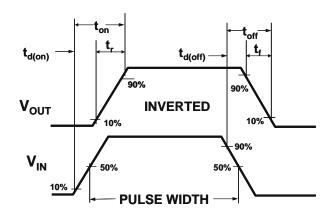


Figure 2:Switching Waveforms

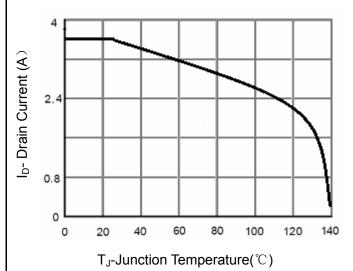
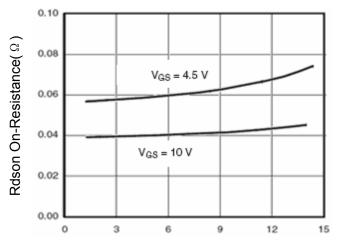


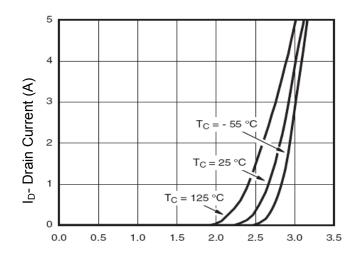
Figure 4 Drain Current



I_D- Drain Current (A)

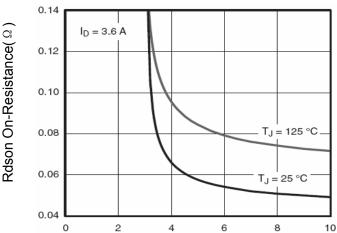
Figure 6 Drain-Source On-Resistance





Vgs Gate-Source Voltage (V)





Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

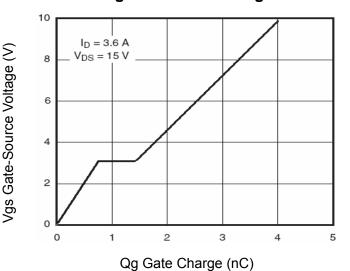
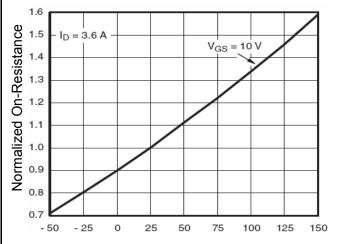
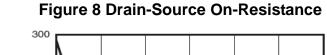
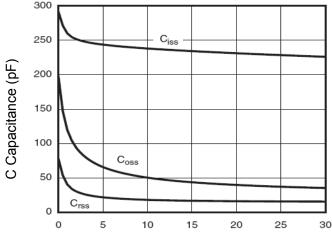


Figure 11 Gate Charge



 T_J -Junction Temperature($^{\circ}$ C)





Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds

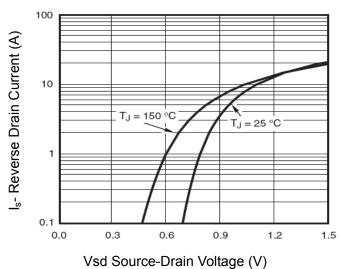
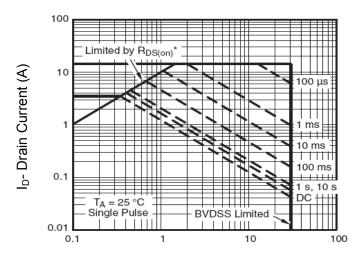


Figure 12 Source- Drain Diode Forward





Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area

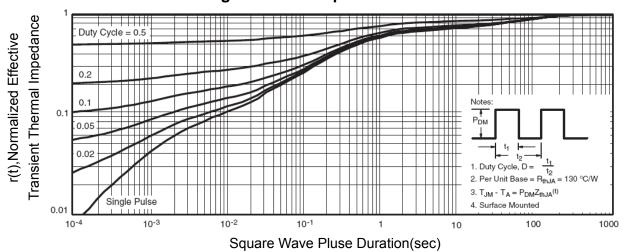
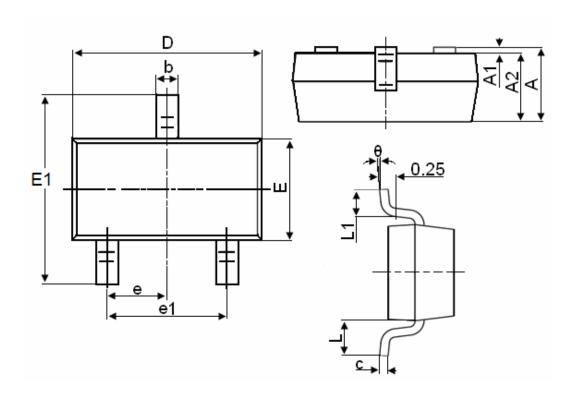


Figure 14 Normalized Maximum Transient Thermal Impedance



SOT-23 Package Information



Symbol	Dimensions in Millimeters				
Symbol	MIN.	MAX.			
Α	0.900	1.150			
A1	0.000	0.100			
A2	0.900	1.050			
b	0.300	0.500			
С	0.080	0.150			
D	2.800	3.000			
E	1.200	1.400			
E1	2.250	2.550			
е		0.950TYP			
e1	1.800	2.000			
L	0.550REF				
L1	0.300	0.500			
θ	0°	8°			

Notes

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



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